

AB-PL1717D058-3V83

Introduction

AB-PL1717D058-3V83 is one of the smallest and thinnest high power CSP LED footprint available, it offers extended solid-state lighting design possibilities.

The 1717's combination of consistent design across all configurations and its small size permit improved color mixing and optical control, compared to the larger 3535 LED. It is designed with unique packaging and super thin substrate technology which providing superior high stability reliability.

It qualifies as the JEDEC Level 1 MSL sensitivity level and suitable for SMD process, Pb-free reflow soldering capability, and full compliance with EU Reduction of Hazardous Substances (RoHS) legislation.

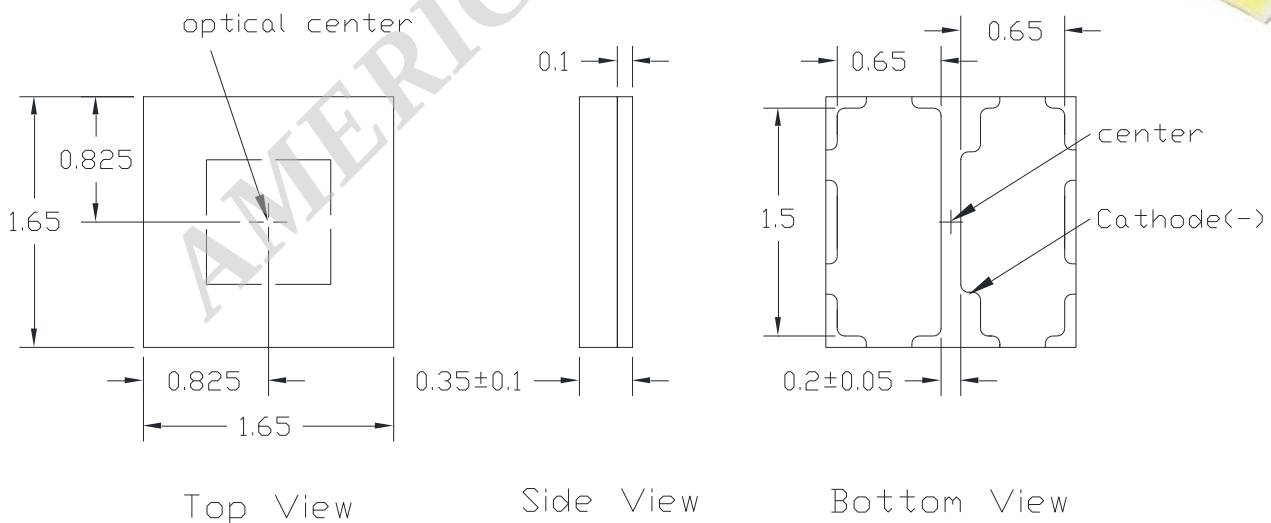
Features

1. Very wide viewing angle
2. Thinner product with pad extension chip technology
3. Flip chip technology
4. RoHS compliant

Main Applications

- Entertainment Lighting
- Commercial Lighting
- Indoor Lighting
- Outdoor Lighting
- Warning Light
- Stage lighting
- Consumer Portable
- Architectural
- Head up display (HUD)

Emitter Mechanical Dimensions



Notes:

1. Drawing not to scale.
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are $\pm 0.15\text{mm}$.
4. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
5. Please do not use a force of over 0.3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

AB-PL1717D058-3V83

Flux Characteristics, $T_J = 25^\circ\text{C}$

Color	Part Number Emitter	Luminous Flux Φ_v (lm)		
		Min.	@350mA Typ.	Refer @700mA Typ.
White	AB-PL1717D058-3V83	116	140	240

- AB maintains a tolerance of $\pm 7\%$ on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics, $T_J = 25^\circ\text{C}$

Color	Forward Voltage V_F (V)			Thermal Resistance Junction to Slug ($^\circ\text{C}/\text{W}$)
	Min.	@350mA Typ.	Max.	Refer @700mA Typ.
White	2.60	3.00	3.40	3.15
				5

- AB maintains a tolerance of $\pm 0.1\text{V}$ for Voltage measurements.

Optical Characteristics at 350mA, $T_J = 25^\circ\text{C}$

Radiation Pattern	Color	Color Temperature CCT			Total included Angle (degrees)	Viewing Angle (degrees)
		Min.	Typ.	Max.	$\theta_{0.90V}$	$2\theta_{1/2}$
Flat	White	4800 K	5800 K	6970 K	170	120

- AB maintains a tolerance of $\pm 5\%$ for CCT measurements.

AB-PL1717D058-3V83

Absolute Maximum Ratings

Parameter	White
DC Forward Current (mA)	700
Peak Pulsed Forward Current (mA)	1000 (less than 1/10 duty cycle@1KHz)
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	2KV
LED Junction Temperature	135°C
Operating Board Temperature at Maximum DC Forward Current	-40°C - 105°C
Storage Temperature	-40°C - 135°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

Photometric Luminous Flux Bin Structure at 350mA

Color	Bin Code	Minimum Photometric Flux (lm)	Maximum Photometric Flux (lm)	Available Color Bins
White	V1	116	120	All
	V2	120	130	W2, W3, X1, X4 ^[1]
	W1	130	140	[1]
	W2	140	155	[1]
	X1	155	170	[1]
	X2	170	185	[1]

- AB maintains a tolerance of $\pm 7\%$ on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- ^[1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Forward Voltage Bin Structure at 350mA

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
White	a	2.6	2.8
	A	2.8	3.0
	B	3.0	3.2
	D	3.2	3.4

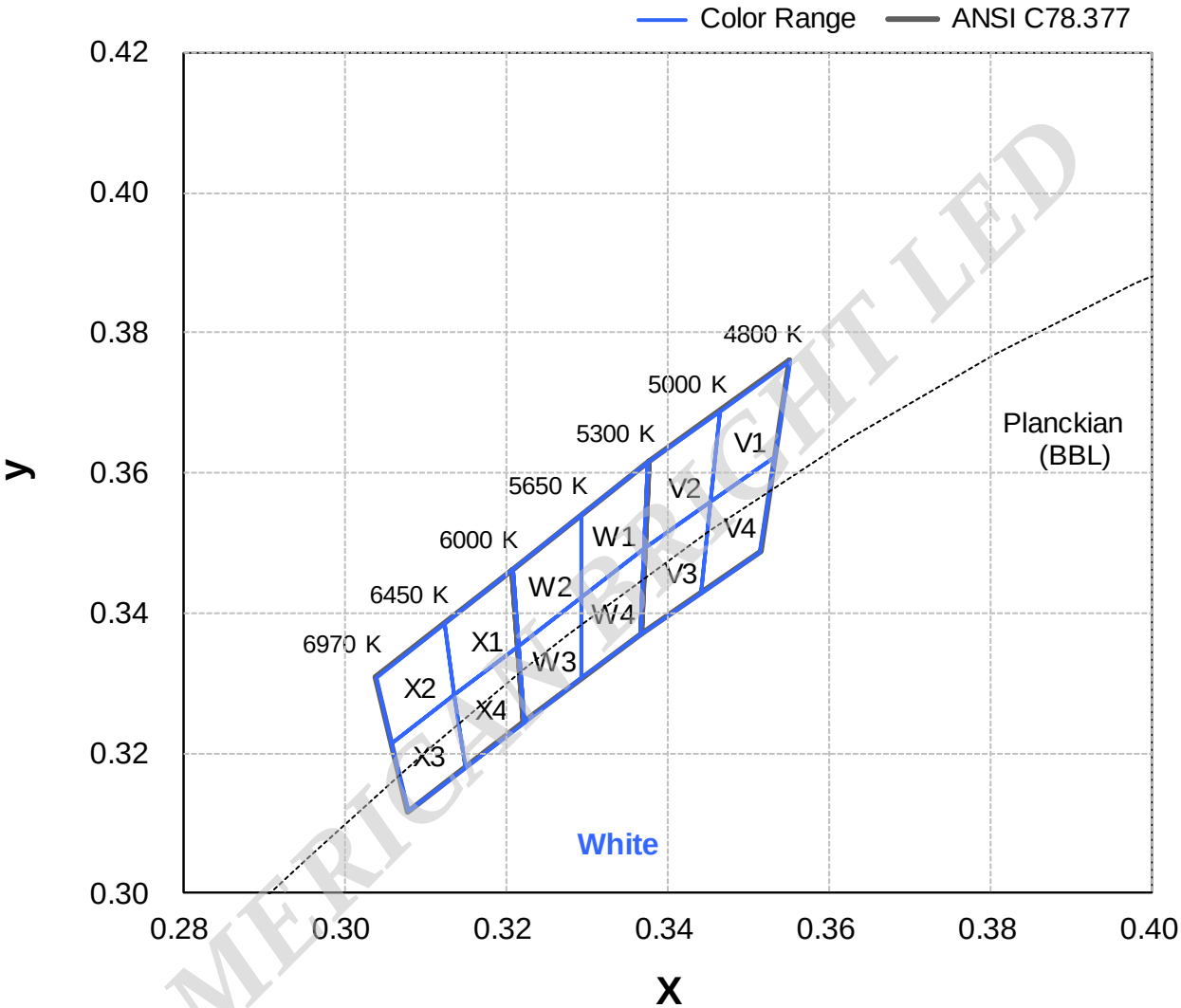
- AB maintains a tolerance of $\pm 0.1V$ for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

AB-PL1717D058-3V83

Color Bin

White Binning Structure Graphical Representation



AB-PL1717D058-3V83

Color Bin

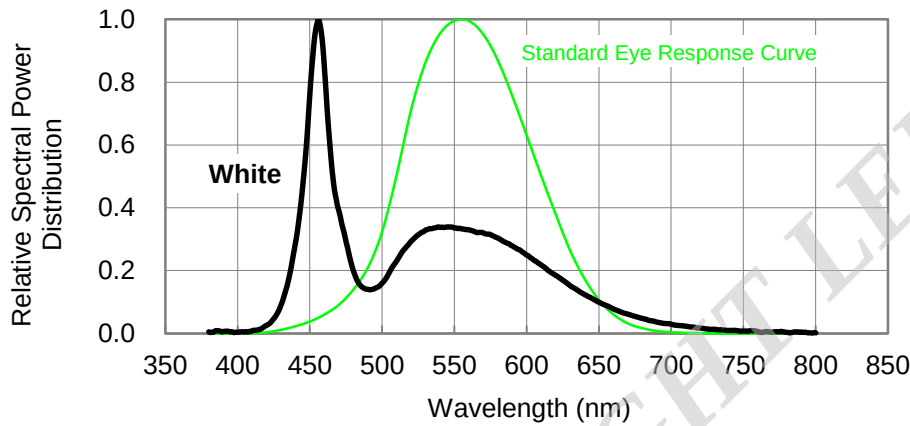
White Bin Structure

Bin Code	x	y	Typ. CCT (K)	Bin Code	x	y	Typ. CCT (K)
V1	0.3464	0.3688	4870	W2	0.3207	0.3462	5830
	0.3551	0.3760			0.3292	0.3539	
	0.3533	0.3624			0.3293	0.3423	
	0.3452	0.3558			0.3215	0.3353	
V4	0.3452	0.3558	4870	W3	0.3215	0.3353	5830
	0.3533	0.3624			0.3293	0.3423	
	0.3515	0.3487			0.3294	0.3306	
	0.3441	0.3428			0.3222	0.3243	
V2	0.3376	0.3616	5155	X1	0.3123	0.3385	6240
	0.3464	0.3688			0.3207	0.3462	
	0.3452	0.3558			0.3215	0.3353	
	0.3371	0.3493			0.3136	0.3283	
V3	0.3371	0.3493	5155	X4	0.3136	0.3283	6240
	0.3452	0.3558			0.3215	0.3353	
	0.3441	0.3428			0.3222	0.3243	
	0.3366	0.3369			0.3150	0.3180	
W1	0.3292	0.3539	5475	X2	0.3038	0.3308	6700
	0.3376	0.3616			0.3123	0.3385	
	0.3371	0.3493			0.3136	0.3283	
	0.3293	0.3423			0.3058	0.3213	
W4	0.3293	0.3423	5475	X3	0.3058	0.3213	6700
	0.3371	0.3493			0.3136	0.3283	
	0.3366	0.3369			0.3150	0.3180	
	0.3294	0.3306			0.3078	0.3117	

- Tolerance on each color bin (x , y) is ± 0.005

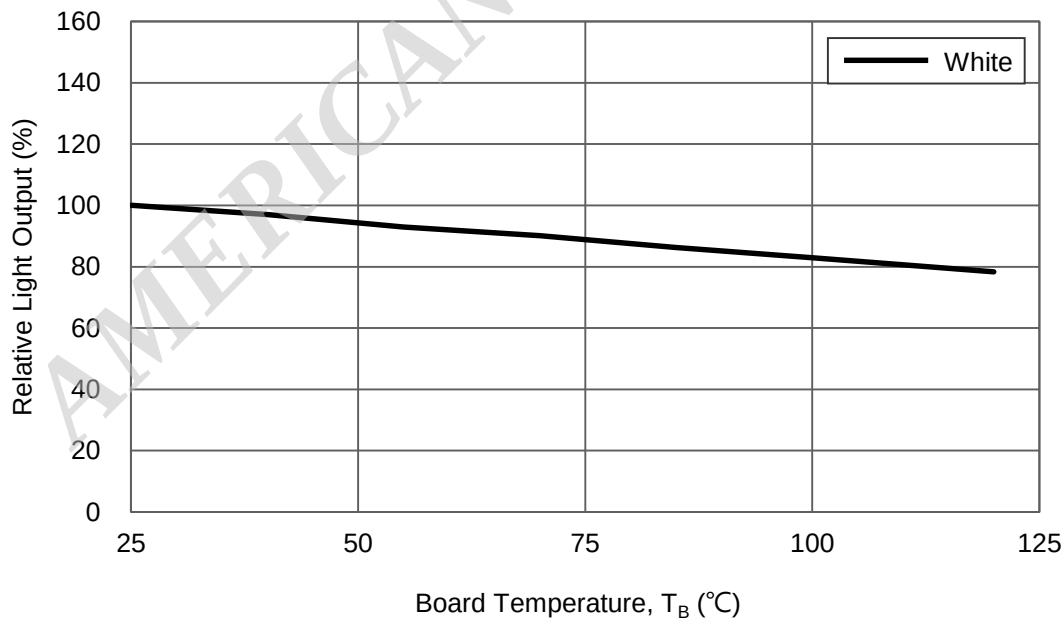
Color Spectrum, $T_J = 25^{\circ}\text{C}$

1. White



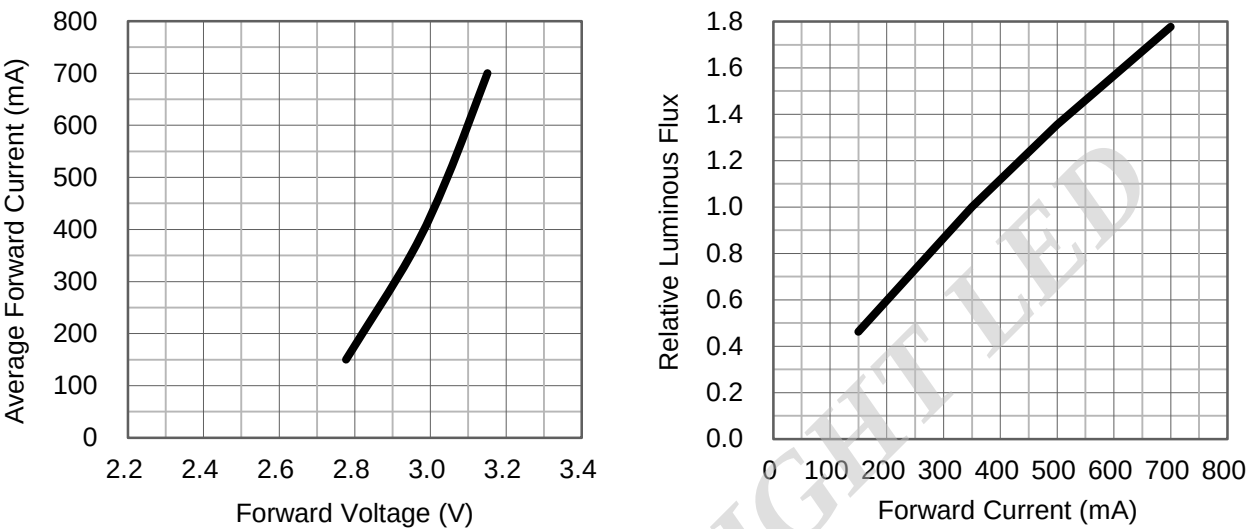
Light Output Characteristics

Relative Light Output vs. Board Temperature at 350mA

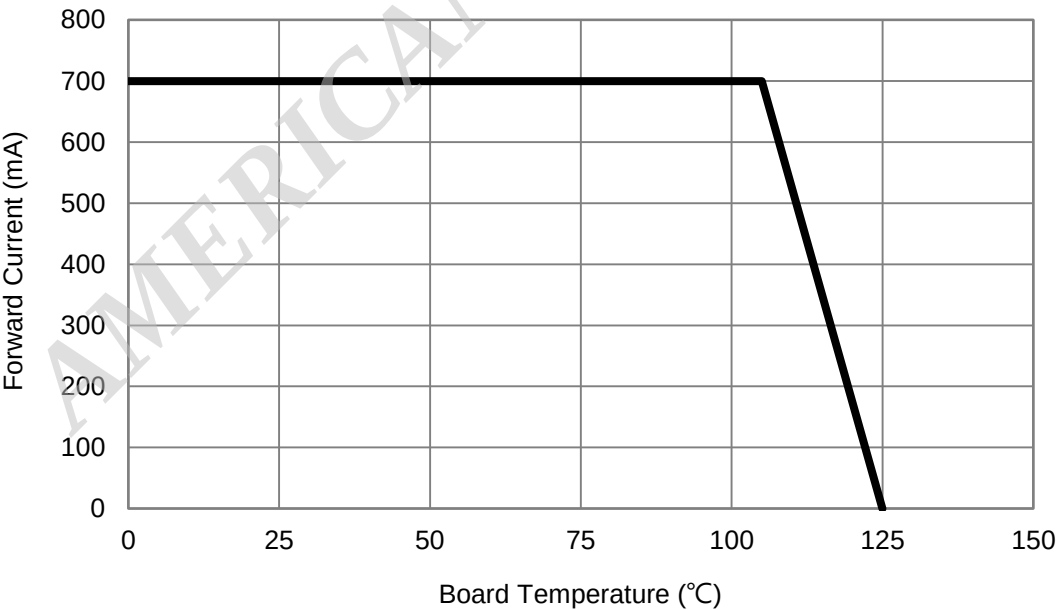


AB-PL1717D058-3V83

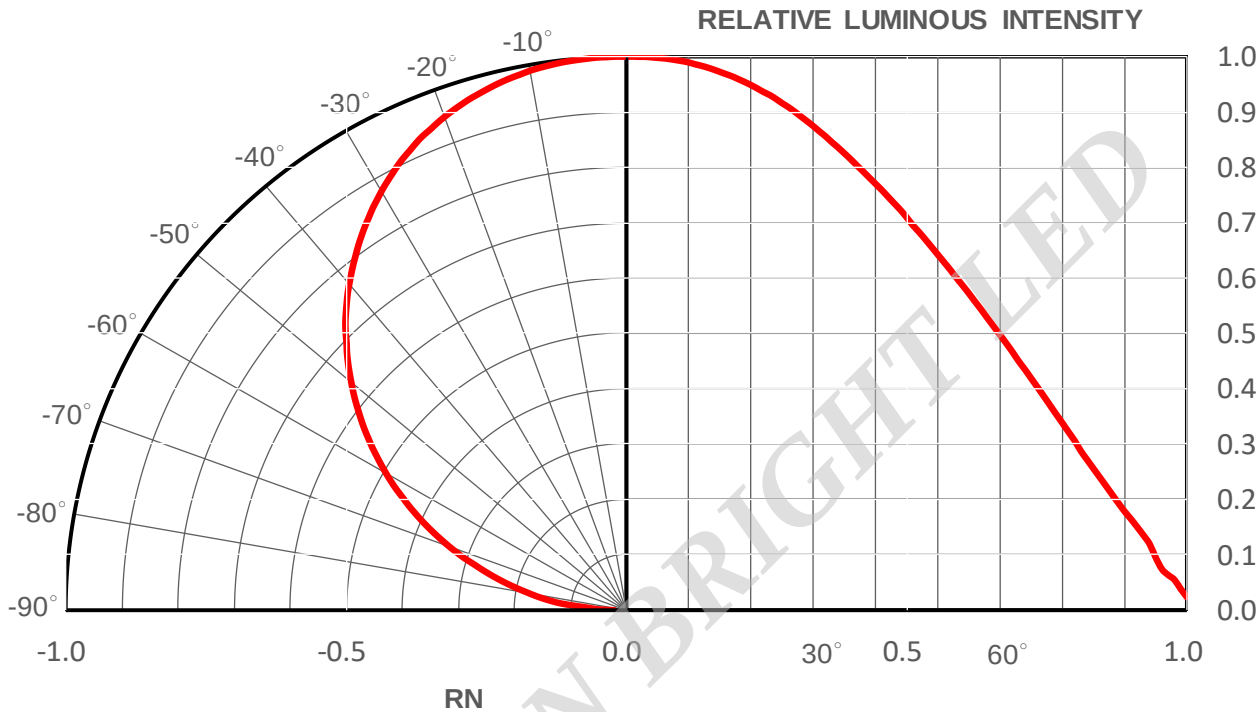
Forward Current Characteristics, $T_J = 25^{\circ}\text{C}$



Board Temperature vs. Maximum Forward Current



Typical Representative Spatial Radiation Pattern



AB-PL1717D058-3V83

Moisture Sensitivity Level - JEDEC Level 1

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufacture's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA

AB-PL1717D058-3V83

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

- Depending on the maximum derating curve.
- Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	I_F = max DC	--	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	I_F = max DC	Initial Level x 0.7	--
Reverse Current (I_R)	V_R = 5V	--	50 μ A

* The test is performed after the LED is cooled down to the room temperature.

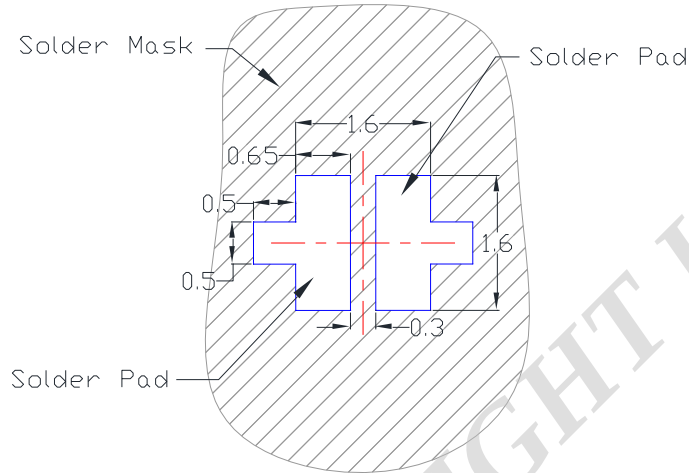
- A failure is an LED that is open or shorted.

AB-PL1717D058-3V83

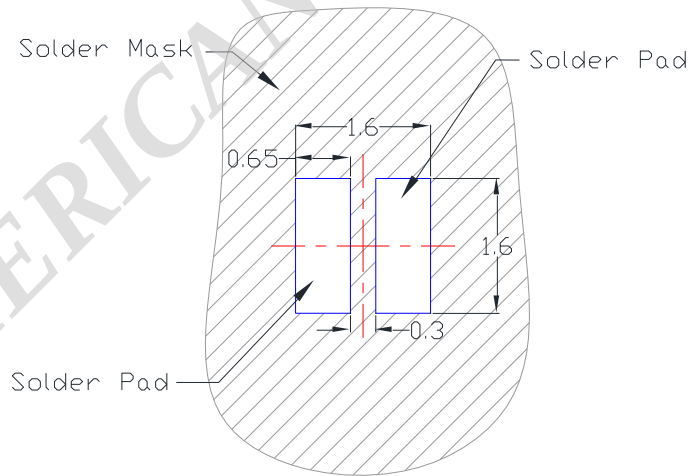
Recommended Solder Pad Design

Standard Emitter

TYPE A.



TYPE B.

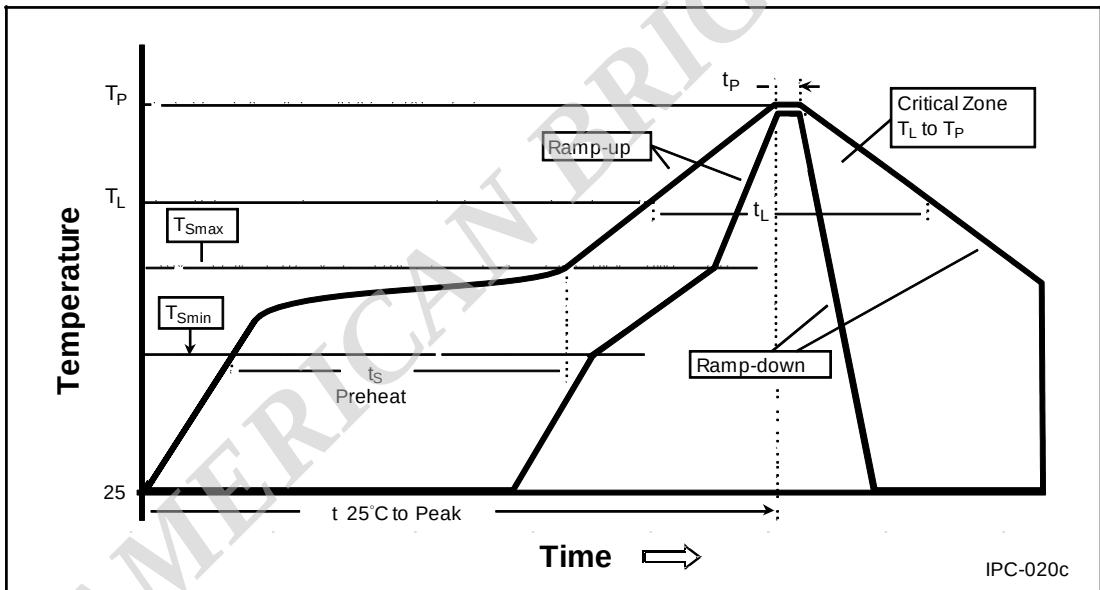


- All dimensions are in millimeters.

AB-PL1717D058-3V83

Reflow Soldering Condition

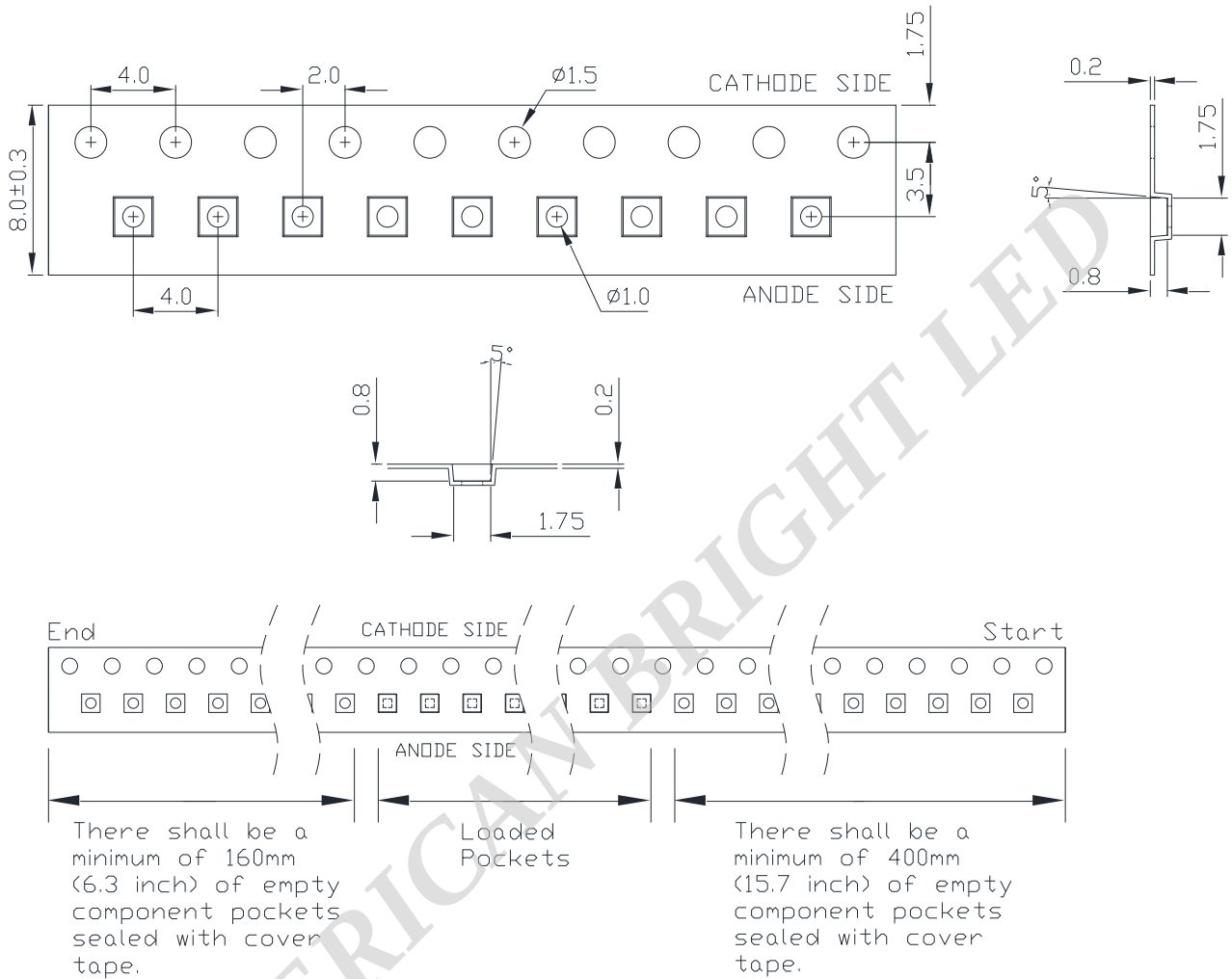
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_P)	3°C / second max.	3°C / second max.
Preheat – Temperature Min (T_{Smin}) – Temperature Max (T_{Smax}) – Time (t_{Smin} to t_{Smax})	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: – Temperature (T_L) – Time (t_L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (T_P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_P)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue > 47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

AB-PL1717D058-3V83

Emitter Reel Packaging

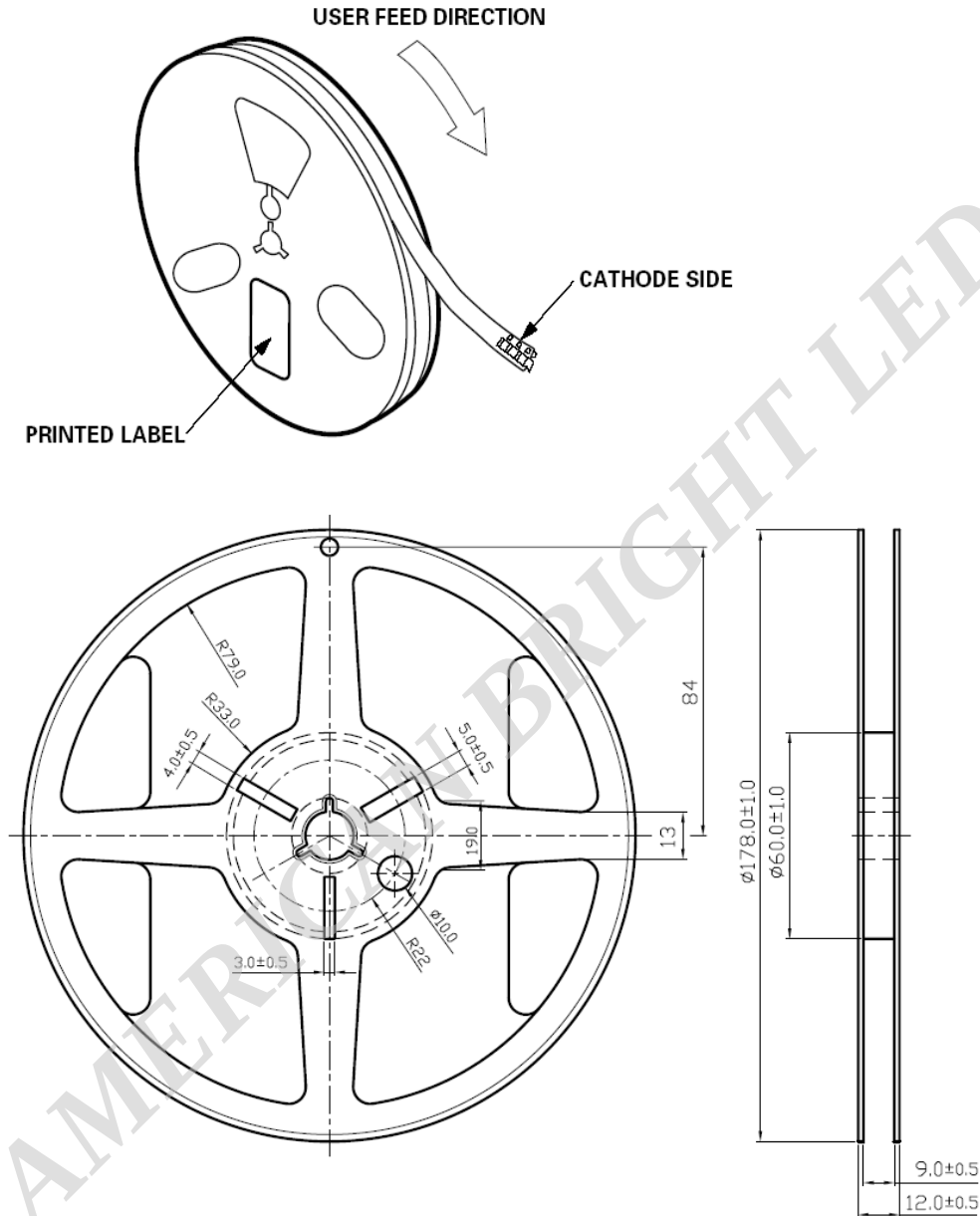


Notes:

1. Drawing not to scale.
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are ± 0.1 mm.

AB-PL1717D058-3V83

Emitter Reel Packaging



Notes:

1. Empty component pockets sealed with top cover tape.
2. 2000 and 4000 pieces per reel.
3. Drawing not to scale.
4. All dimensions are in millimeters.

Precaution for Use

- Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- The slug is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue > 47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice.

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 0.3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)

